



Click [here](#) for the 3D model.

Dimensions	
Footprint	7343
L	7.3mm +/-0.3mm
W	4.3mm +/-0.3mm
H	2.8mm +/-0.3mm
T	0.13mm REF
S	1.3mm +/-0.3mm
F	2.4mm +/-0.1mm
A	3.6mm MIN
B	0.5mm +/-0.15mm
E	3.5mm REF
G	3.5mm REF
P	0.9mm REF
R	1mm REF
X	0.1mm +/-0.1mm REF

Packaging Specifications	
Packaging	T&R, 178mm
Packaging Quantity	500

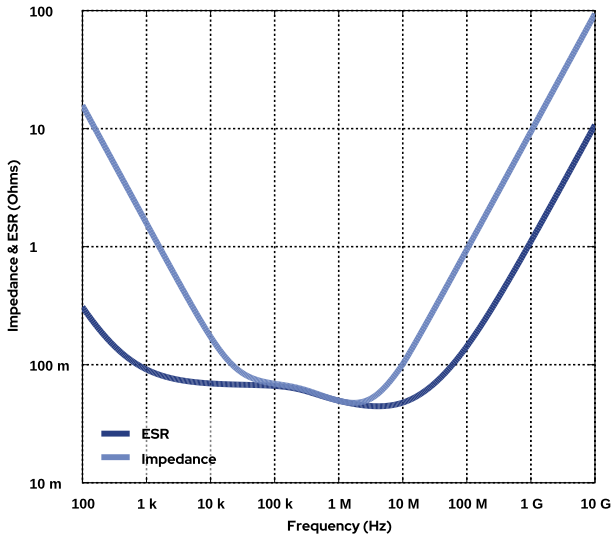
General Information	
Series	T491 Auto
Dielectric	MnO ₂ Tantalum
Style	SMD Chip
Description	SMD, MnO ₂ , Molded, Auto, AEC-Q200
Features	Automotive
RoHS	Yes
Termination	Tin
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	446.84 mg

Specifications	
Capacitance	100 uF
Capacitance Tolerance	10%
Voltage DC	16 VDC (85C), 10.72 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	8% 120Hz 25C
Failure Rate	N/A
ESR	0.7 Ohms (100kHz 25C)
Ripple Current	463 mA (rms, 100kHz 25C)
Leakage Current	16 uA (5min 25°C)

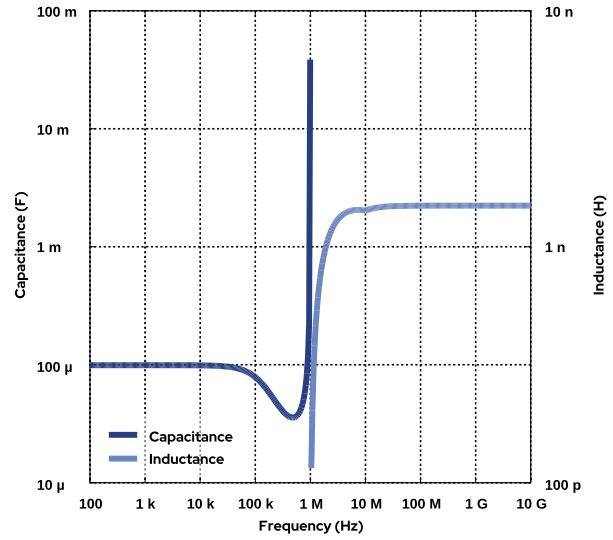
Simulations

For the complete simulation environment please visit [K-SIM](#).

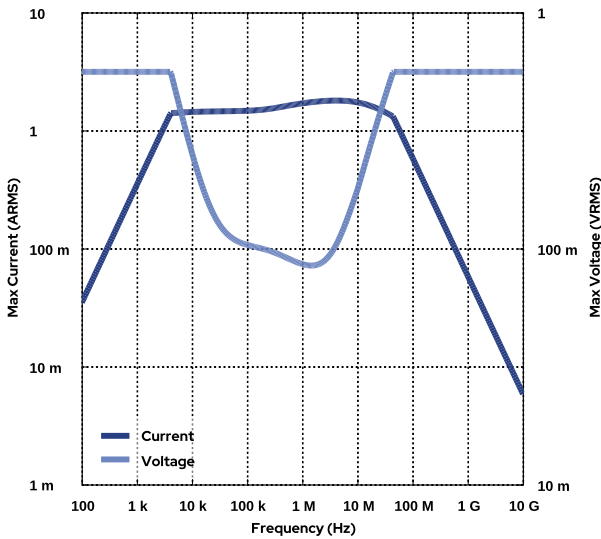
Impedance and ESR



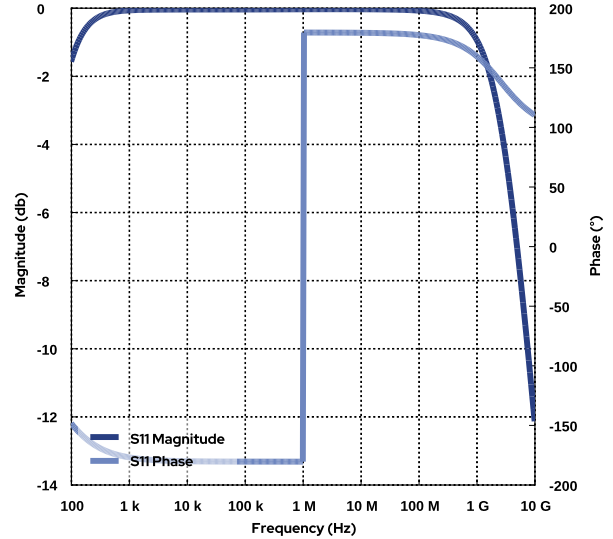
Capacitance and Inductance



Current and Voltage



S11

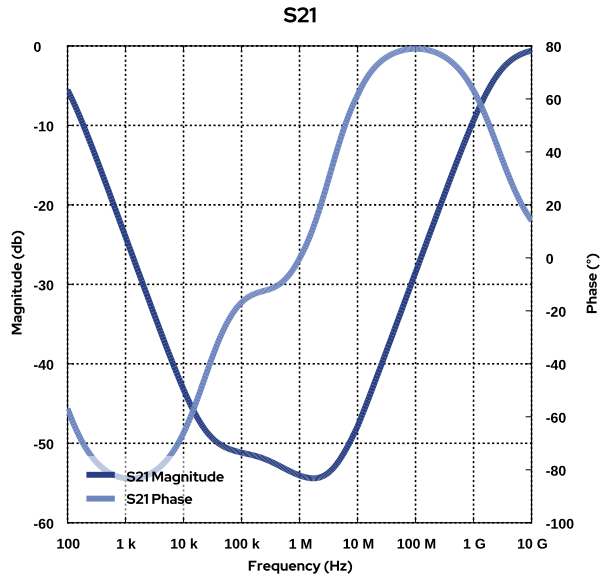




a YAGEO company

T491D107K016ATAUTO

T491 Auto, Tantalum, MnO2 Tantalum, Commercial Grade, 100 uF, 10%, 16 VDC, SMD, MnO2, Molded, Auto, AEC-Q200, 700 mOhms, 7343, 3.1mm



These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (R_{th}) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
- The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.